

Dip Stencil 40 x 40 mm, 300 µm, for Dip and Print Station - Ersä OPR100-D001

Item no. ER-OPR100-D001

Manufacturer Ersä

EAN 4003008090796

Dip stencil 40 x 40 mm with a 300 µm foil thickness for the Ersä Dip and Print Station OPR100. By dipping the component it deposits a defined amount of flux or solder paste at the solder joints. Suitable for BGA and most fine-pitch components.

TECHNICAL DATA

Ausführungsklasse	TEC
Country of Manufacture	Germany
ESD equipment	ESD Lötstationen
Weight	0.1 kg



DESCRIPTION

The Ersä dip stencil 40 x 40 mm is used for component preparation on the Ersä Dip and Print Station OPR100. By dipping the component, a defined depot of flux or solder paste is created at the solder joints - suitable for BGA and most fine-pitch components.

TECHNICAL DATA

Type	Dip stencil
Dimensions	40 x 40 mm
Foil thickness	300 µm
Compatible with	Ersä Dip and Print Station OPR100
Application	Flux or solder paste application, BGA and fine-pitch
Manufacturer part number	OPR100-D001
EAN	4003008090796